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TN  
1/24/08*

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of: Adrian E. Ong  
Title: Layout And Use Of Bond Pads And Probe Pads For  
Testing Of Integrated Circuits Devices  
Application No.: 10/003,375  
Filing Date: November 15, 2001  
Examiner: Tung X. Nguyen  
Group Art Unit: 2829  
Confirmation No.: 4697  
Law Office: Sidley Austin Brown & Wood LLP  
Mail Stop AF  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

**RESPONSE TO FINAL OFFICE ACTION**

Dear Sir:

This is a Response to the Final Office Action dated August 24, 2005 for the above-referenced Application. Applicant respectfully requests reconsideration of the Application in view of the following amendments and remarks.